



Thermal CFP2000-US 碳纤维高导热垫片采用碳纤维定向排列技术进行制备，其具有超高的导热系数 20.0W/m.K，同时具备良好的力学性能。该产品具有较强的弥合公差能力，可有效提升芯片散热效率。

Thermal CFP2000-US carbon fiber based high thermal conductive gap pad is designed based on carbon fiber orientation technology with thermal conductivity of 20.0W/m.K. The product provides good mechanical properties, as well as excellent gap filling ability to improve chip dissipation efficiency.

Features 特性

- Thermal Conductivity
导热系数 20.0 W/m·K
- Low Compress Stress
低压缩应力
- High Rebound Performance
高回弹
- High Reliability 高可靠性

Applications 产品应用

- Consumer Electronics
消费电子
- Network Equipment
网通设备
- Data Center 数据中心
- Optical Module 光模块
- Projector 投影仪

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Carbon Filler and Thermal Powder 硅胶&碳纤维&导热粉体		—
Color 颜色	Dark Gray 深灰色	—	Visual 目视
Thermal Conductivity 导热系数	20.0	W/m·K	ASTM D5470
Thickness 厚度	0.3 - 5.0	mm	ASTM D374
Hardness 硬度 (Shore 00)	35	—	ASTM D2240
Density 密度	1.9	g/cm ³	ASTM D792
Temperature Range 耐温范围	-40 - 200	°C	—
Breakdown Voltage 击穿强度	< 100	V/mm	ASTM D149
Volume Resistivity 体积电阻率	< 500	Ω.cm	ASTM D257
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	24	month	25±5°C ≤50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

此技术资料里所有陈述的技术信息，全部是基于本公司对自身产品在经过严格的测试评估后，证明各项技术参数指标是值得信赖的前提下编写的。在您使用我们公司产品之前，请充分评估该产品是否符合您的使用需求，您需要承担使用的全部风险和责任。